## Tender for re-opening of 10-year Government Bonds under Institutional Bond Issuance Programme to be held on November 29

The following is issued on behalf of the Hong Kong Monetary Authority:

The Hong Kong Monetary Authority (HKMA), as representative of the Hong Kong Special Administrative Region Government (HKSAR Government), announced today (November 20) that a tender of five-year Government Bonds (Bonds) through the re-opening of existing 10-year Government Bond issue 10GB2706 under the Institutional Bond Issuance Programme will be held on November 29, 2023 (Wednesday), for settlement on November 30, 2023 (Thursday).

An additional amount of HK\$3.0 billion of the outstanding 10-year Bonds (issue no. 10GB2706) will be on offer. The Bonds will mature on June 29, 2027 and will carry interest at the rate of 1.25 per cent per annum payable semi-annually in arrears. The Indicative Pricings of the Bonds on November 20, 2023 are 91.58 with an annualised yield of 3.804 per cent.

Under the Institutional Bond Issuance Programme, tender is open only to Recognized Dealers which are appointed as Primary Dealers. Anyone wishing to apply for the Bonds on offer can do so through any of the Primary Dealers on the current published list, which can be obtained from the Hong Kong Government Bonds website at <a href="https://www.hkgb.gov.hk">www.hkgb.gov.hk</a>. Each tender must be for an amount of HK\$50,000 or integral multiples thereof.

Tender results will be published on the HKMA's website, the Hong Kong Government Bonds website, the Refinitiv screen (HKGBINDEX), and Bloomberg (GBHK <GO>) not later than 3pm on the tender day.

HKSAR Government Institutional Bond Issuance Programme Tender Information

Tender information of re-opening of 10-year Government Bonds under the Institutional Bond Issuance Programme:

Issue Number : 10GB2706 (Re-open)
Stock Code : 4235 (HKGB 1.25 2706)

Tender Date and November 29, 2023 (Wednesday)

Time : 9.30am to 10.30am

Issue and

Settlement Date : November 30, 2023 (Thursday)

for Tender Amount

Amount on Offer : HK\$3.0 billion

Maturity : 5 years

Remaining Maturity

: Approximately 3.58 years

Maturity Date

: June 29, 2027

Interest Rate

1.25 per cent p.a. payable semi-annually in

arrears

December 29, 2023 June 28, 2024 December 30, 2024 June 30, 2025

Interest Payment

Dates

December 29, 2025 June 29, 2026 December 29, 2026 June 29, 2027

Method of Tender

: Competitive tender

Each competitive tender must be for an amount of HK\$50,000 or integral multiples thereof. Any tender applications for the Bonds must be submitted through a Primary Dealer on the current published list.

The accrued interest to be paid by successful bidders on the issue date

Tender Amount

: (November 30, 2023) for the tender amount is

HK\$263.70 per minimum denomination of

HK\$50,000.

(The accrued interest to be paid for tender

amount exceeding HK\$50,000 may not be

exactly equal to the figures calculated from

the accrued interest per minimum

denomination of HK\$50,000 due to rounding).

Please see Information Memorandum available

Other Details

: on the Hong Kong Government Bonds website at <a href="https://www.hkgb.gov.hk">www.hkgb.gov.hk</a> or approach Primary Dealers.

Expected

commencement date

of dealing on the Stock

Exchange of Hong Kong

Limited

The tender amount is fully fungible with the existing 10GB2706 (Stock code: 4235) listed

on the Stock Exchange of Hong Kong.

Price/Yield Table of the Government Bonds at tender (for reference only\*):

Yield-to-Maturity Price		Yield-to-Maturity Price	
2.804	94.81	3.804	91.64
2.854	94.65	3.854	91.49
2.904	94.48	3.904	91.33
2.954	94.32	3.954	91.18

3.004	94.16	4.004	91.03
3.054	94.00	4.054	90.87
3.104	93.84	4.104	90.72
3.154	93.68	4.154	90.57
3.204	93.52	4.204	90.41
3.254	93.37	4.254	90.26
3.304	93.21	4.304	90.11
3.354	93.05	4.354	89.96
3.404	92.89	4.404	89.81
3.454	92.73	4.454	89.66
3.504	92.58	4.504	89.51
3.554	92.42	4.554	89.36
3.604	92.26	4.604	89.21
3.654	92.11	4.654	89.06
3.704	91.95	4.704	88.91
3.754	91.80	4.754	88.76
3.804	91.64	4.804	88.61

## \* Disclaimer

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